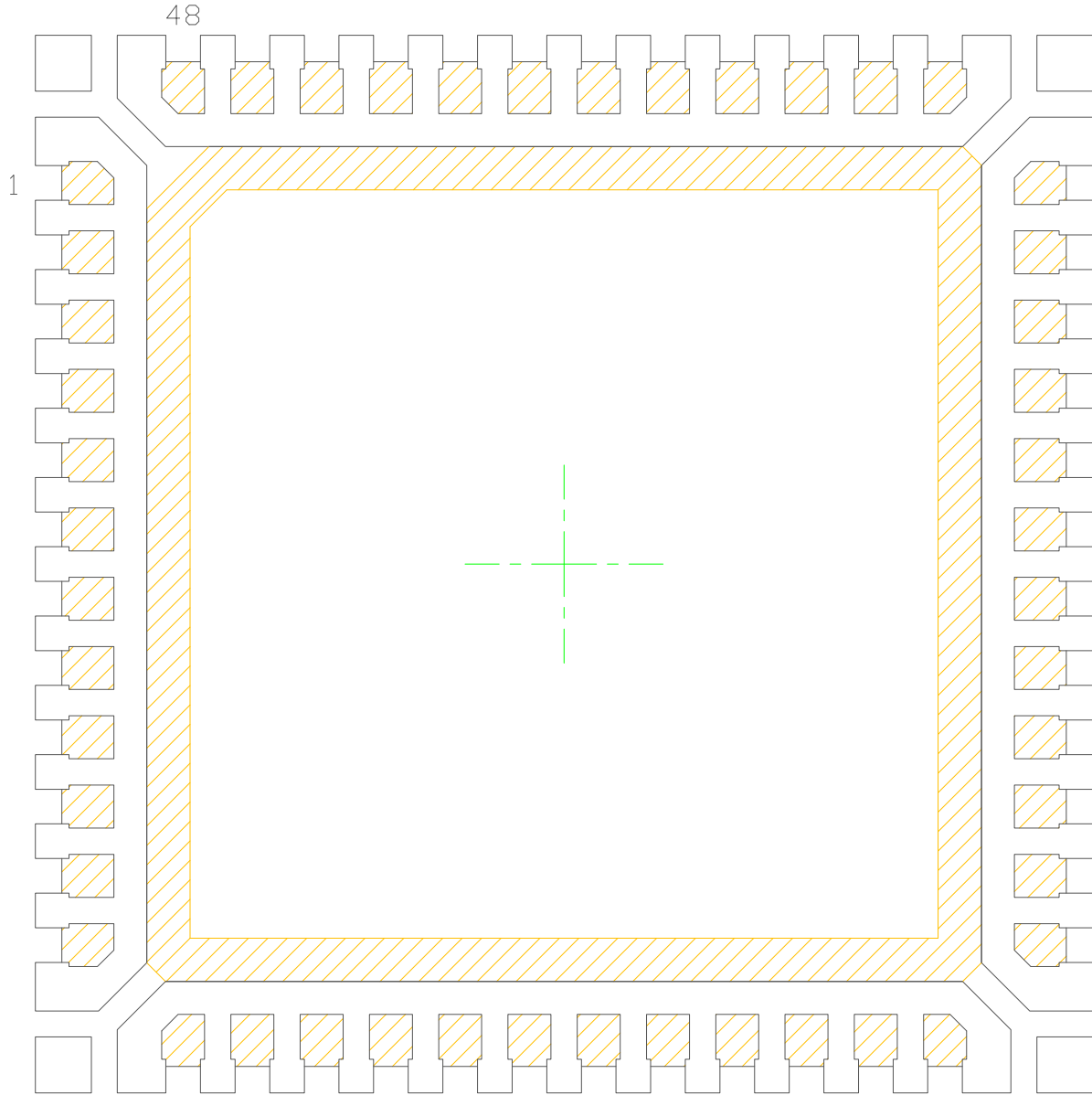



REVISIONS		
REV	DESCRIPTION	DATE
C	INCREASED EXPOSED PAD SIZE, REDUCED GROUND RING WIDTH	07/24/17



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 <a href="http://www.promex-ind.com">www.promex-ind.com</a>	
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 4.82 x 4.82 mm		
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 4.52 x 4.52 mm	TITLE	
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	QFN 48L 6x6 mm 0.40 PITCH BOND SHELL	
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	LEADFRAME P/N:	REV
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	235-00107	00
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE	FILE NAME 48L-QFN-6X6-40P-BD.DWG
			SHEET 1 OF 1